

# FD-SOI: how material & design innovations enable new market opportunities

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Digital Electronics BU - Product Marketing Manager

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# Introduction to Soitec



“ We design and deliver innovative substrates and solutions to enable our customers' products shaping everyday life ”



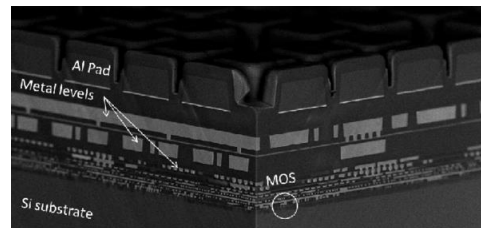
- › **Number 1** – Largest manufacturer of engineered substrates
- › **Global presence** – 1,100 employees worldwide
- › **Serving 4 high-volume markets** – Smartphones, automotive, cloud & infrastructure, IoT
- › **Multi-site industrial footprint** – France, Singapore, China
- › **Industry standard** – RF-SOI is in 100% of smartphones

# Choosing the right base for your product

Pinot Noir, Burgundy, Cabernet Sauvignon...



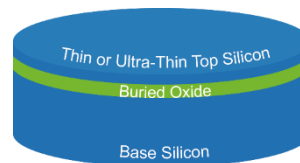
End Product



Soil Properties



Substrate

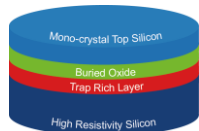


# Soitec's full range of engineered substrates across multiple segments and applications

## RF Front-End Module



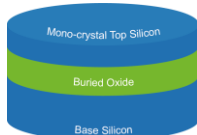
**RF-SOI**  
For high efficient mobile communication



## Power



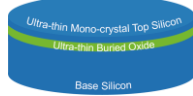
**Power-SOI**  
For seamless high voltage device isolation



## Processor & connectivity SoC



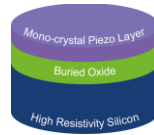
**FD-SOI**  
For power-efficient & flexible digital computing with easy analog/RF integration



## Piezo on insulator



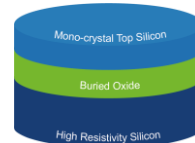
**POI**  
New engineered substrates for filters



## Photonics



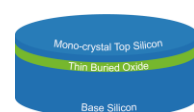
**Photonics-SOI**  
To integrate high performance photonics devices into silicon



## Imagers



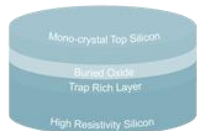
**Imager-SOI**  
For improved imager performance in NIR



# Soitec's full range of engineered substrates across multiple segments and applications

## RF Front-End Module

RF-SOI  
For high efficient mobile communication



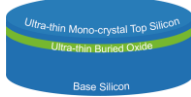
## Power

Power-SOI  
For seamless high voltage device isolation



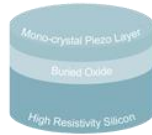
## Processor & connectivity SoC

FD-SOI  
For power-efficient & flexible digital computing with easy analog/RF integration



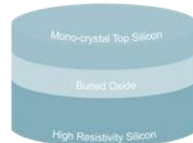
## Piezo on insulator

POI  
New engineered substrates for filters



## Photonics

Photonics-SOI  
To integrate high performance photonics devices into silicon



## Imagers

Imager-SOI  
For improved imager performance in NIR



# AI is about transforming data into meaningful information

$f(\text{data}) = \text{information}$

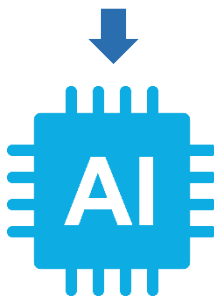
Picture  $f(\text{) = \text{« apple »}$

Motion  $f(\text{) = \text{« maintenance needed »}$

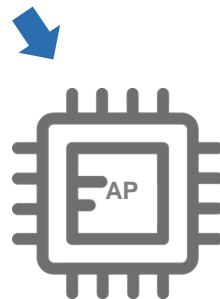
Sound  $f(\text{) = \text{« Hello! »}$



Collect

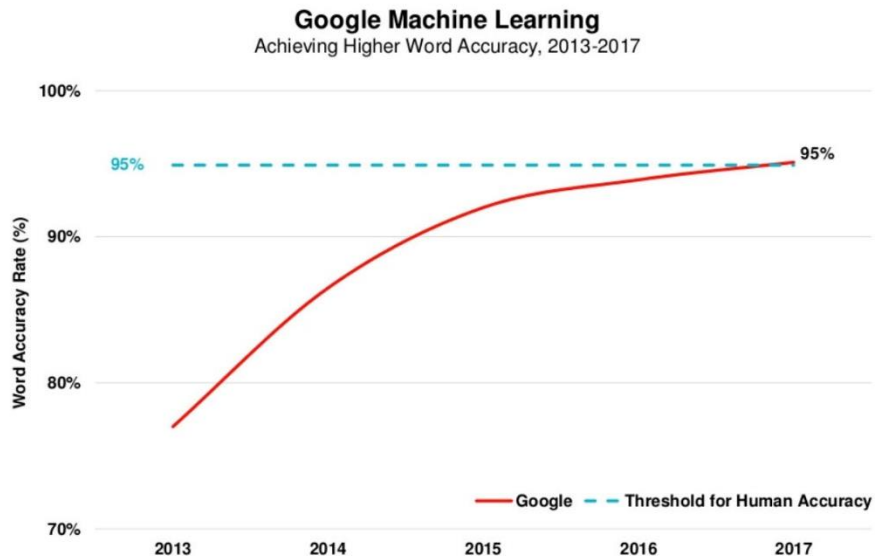


Analyze



Act

# AI is increasingly sophisticated



**Source:** Mary Meeker's annual Internet Trends Report



# AI inference is moving to the edge

## *Low-power solutions are required*

### 4 drivers pushing AI at the edge

Latency / reliability



Data privacy



Power consumption



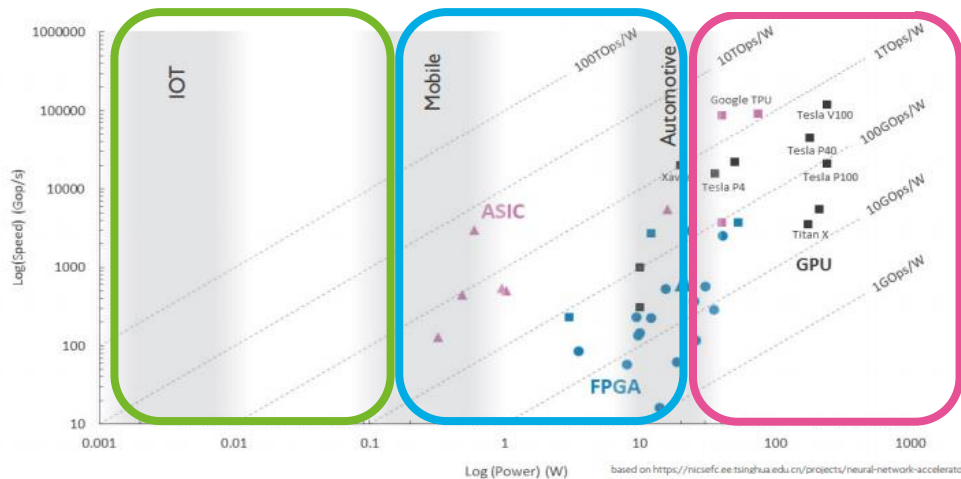
Cost



Very Edge

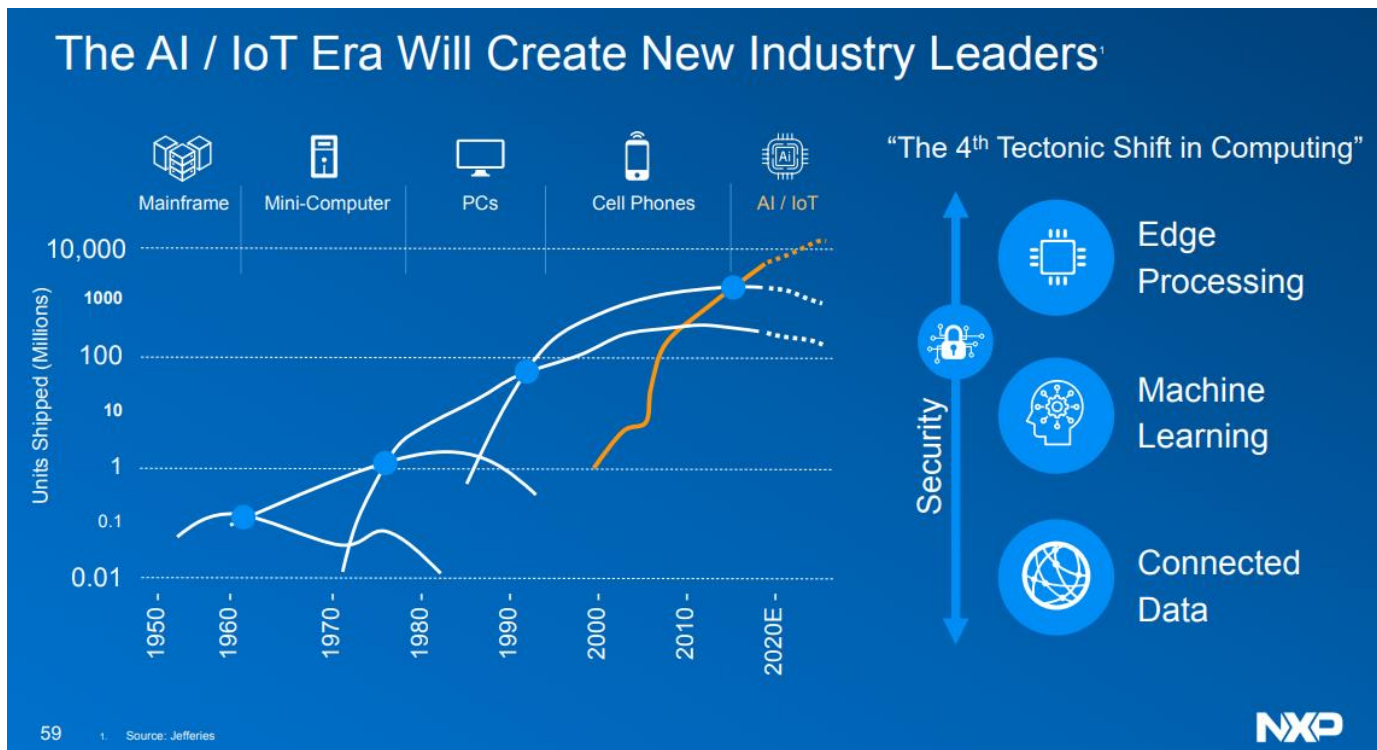
Edge

Cloud



Source: IMEC, ITF2018

# AIoT (AI + IoT) sparks a new semiconductor revolution

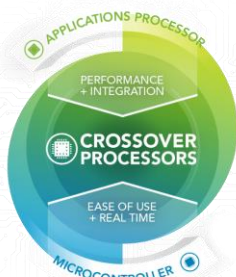


Source: NXP Investor Day 2018

# FD-SOI – powering the AIoT revolution



i.MX RT600 crossover processors unlocking the potential of machine learning and artificial intelligence at the edge, are based on FD-SOI

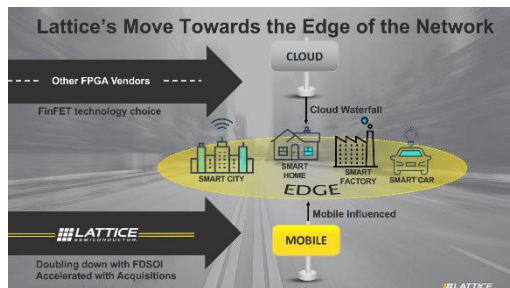


i.MX RT600 Family of Crossover Processors

Powering the next generation of voice-assisted end nodes



Next generation always-on FPGA low power machine learning inferencing (from 1mW to 1W) based on FD-SOI



“ Designers need silicon that allows them to build compact high-performance AI devices that deliver excellent performance without violating footprint or thermal management constraints. Cost is also a crucial factor. ”

Source: Lattice white paper, May 2018



Next generation Human Machine Interfaces powered by AI ambient computing based on FD-SOI



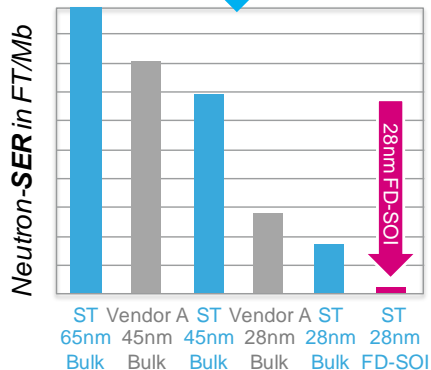
“ The intelligence has to move to the edge [..]. Our vision requires a few things [..]. 22FDX has that mix of performance and power and the ability to aggregate functions such as RF or non-volatile memory that we are looking towards. We need also extremely low power so the ability to do active body biasing is very important to us. ”

Source: Synaptics CEO, GTC, September 2018

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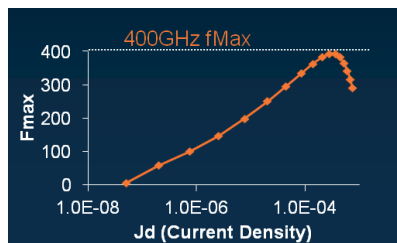
# FD-SOI unique features

## Reliability



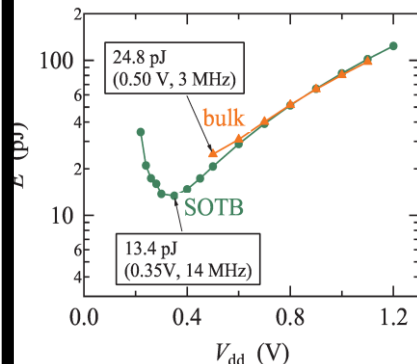
**20x Soft Error Rate improvement vs. bulk**

## mmWave RF-CMOS



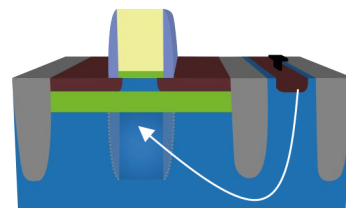
**Best CMOS mmWave with similar performance to SiGe radios**

## Ultra Low Voltage



**Operation at minimum energy point (<0.4V)**

## Body Bias

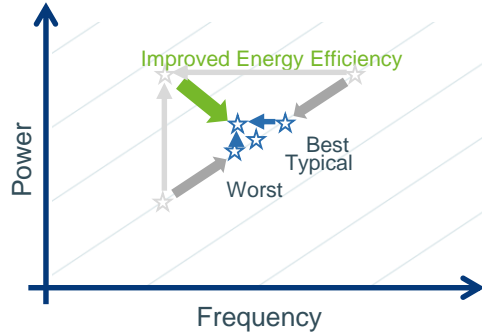


**Up to 7X energy efficiency gains at ULV**

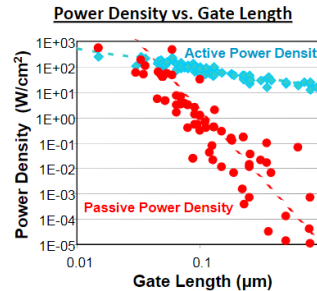
# Energy efficiency needs dynamic power/ leakage optimization techniques



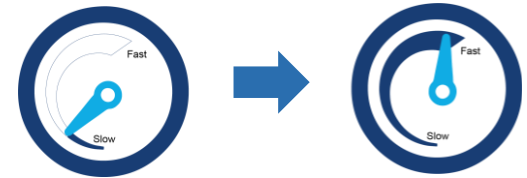
Ultra Low Power  
Energy Efficiency



Variations need to be mitigated for  
optimized energy efficiency



Source: B. Meyerson (IBM)  
Semico Conf., January 2004

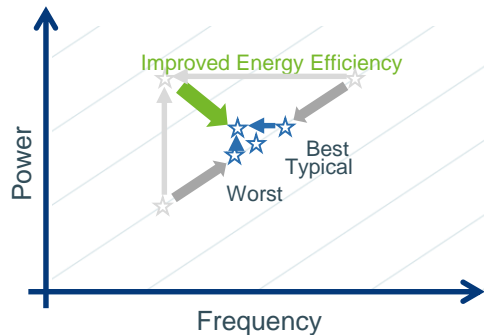


Dynamic Power/ Leakage needs to  
be optimized **real time**

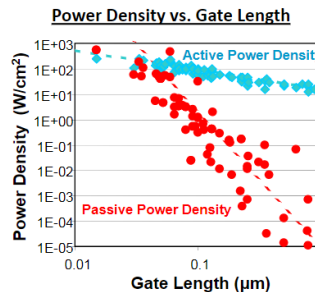
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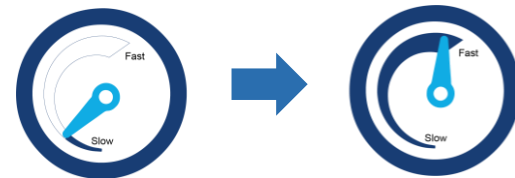
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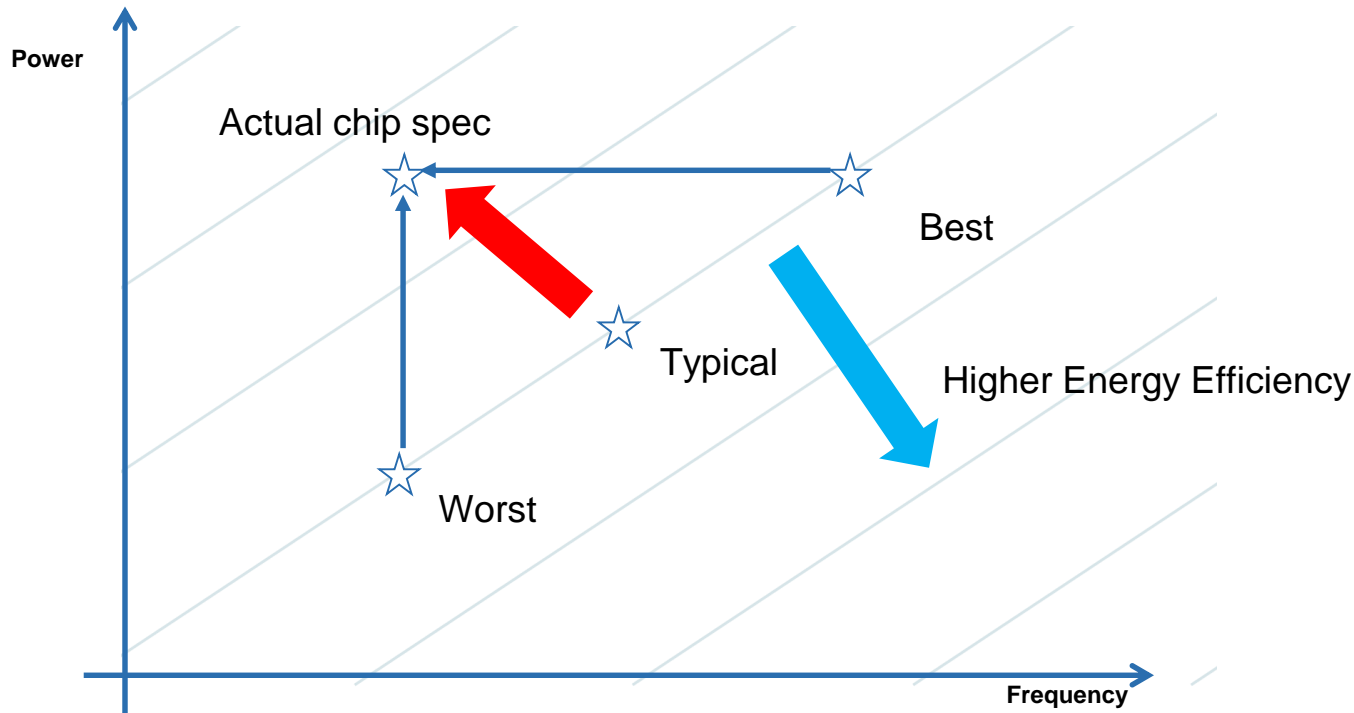


Source: B. Meyerson (IBM)  
Semico Conf., January 2004

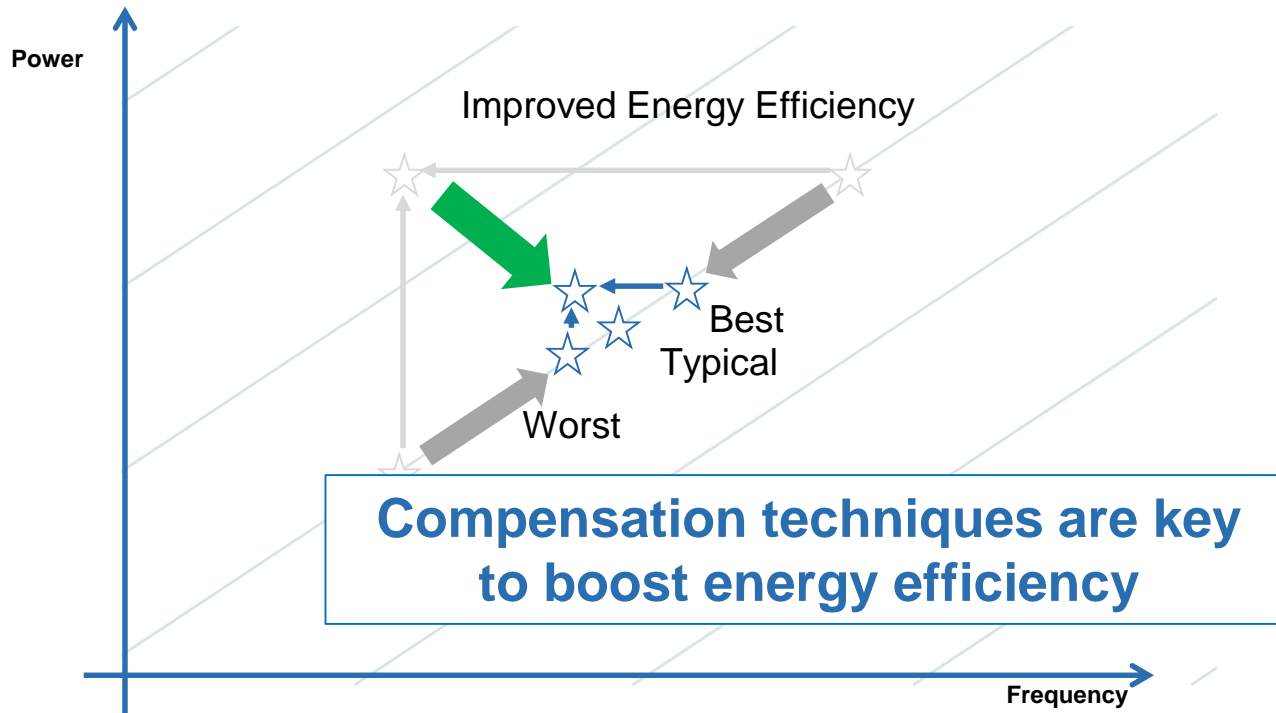


Dynamic Power/ Leakage needs to  
be optimized **real time**

# Variations impact energy efficiency

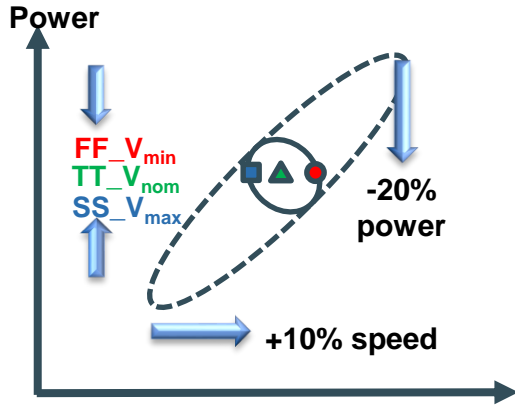


# Variations impact energy efficiency



# Static AVS is commonly used in advanced technology nodes but faces severe drawbacks

## › Performance and power towards TT corner



Process	Voltage	Vfloor	Speed	Power	Aging
■ Slow	High	High	Typical	Typical	High
▲ Typical	Typical	Typical	Typical	Typical	Typical
● Fast	Low	Low	Typical	Typical	Low

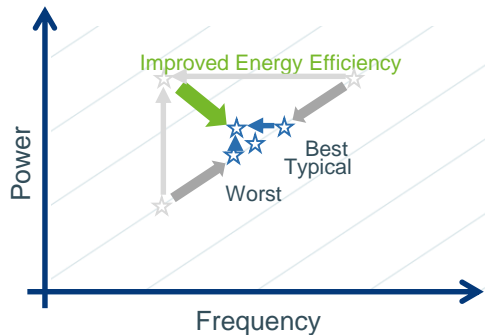
ST, ITC 2017 – Mhira and Huard, Best Paper award

- ! › Aging is degraded
- ! › Vfloor is increased (less room for overdrive)
- ! › Temperature compensation is very difficult (too sensitive). Vdd not the right lever.
- ! › More complex voltage regulators required

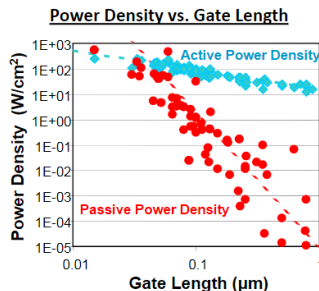
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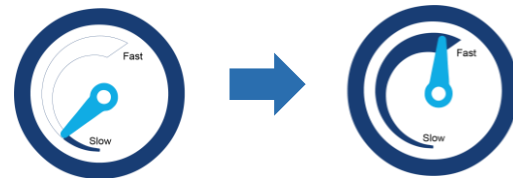
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Source: B. Meyerson (IBM)  
Semico Conf., January 2004

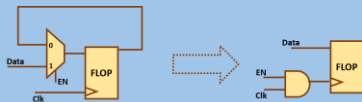


Dynamic Power/ Leakage needs to  
be optimized **real time**

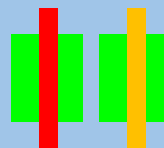
# Low Power design techniques principles

## Clock Gating

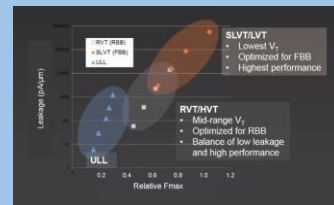
- › Avoid systematic toggling of Flipflops CLK pins
- › Put logic in ClockTree to reduce active power



## Multi-Vth libs



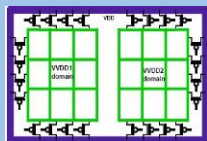
SLVT LVT



Source: GF seminar

## Power Gating

- › Define multi-Vdd domains
  - › High Vdd only on-demand
  - › Low Vdd for low performance



- › Switch off unused domains

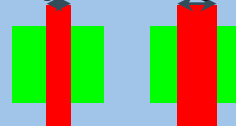
$$\text{Dynamic Power} : \sim W \cdot V_{dd}^2 \cdot F$$

$$\text{Leakage Power} : \sim (V_{dd}/L) \cdot e^{-V_{th}/S}$$

$$\text{Speed} : \sim W/L (V_{dd} - V_{th})^2$$

## Multi gate lengths

Original L Enlarged L



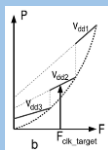
ST, S3S 2017

L <sub>gate</sub>	PB	28FD
Lmin	PB0	1
+4nm	PB4	x4
+10nm	PB10	x10
+16nm	PB16	x30

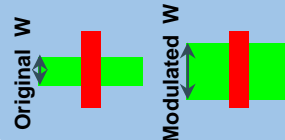
Leakage reduction

## DVFS

- › Dynamic Voltage Frequency Scaling
- › Benefit from  $V^2$  power savings



## Multi drive libs

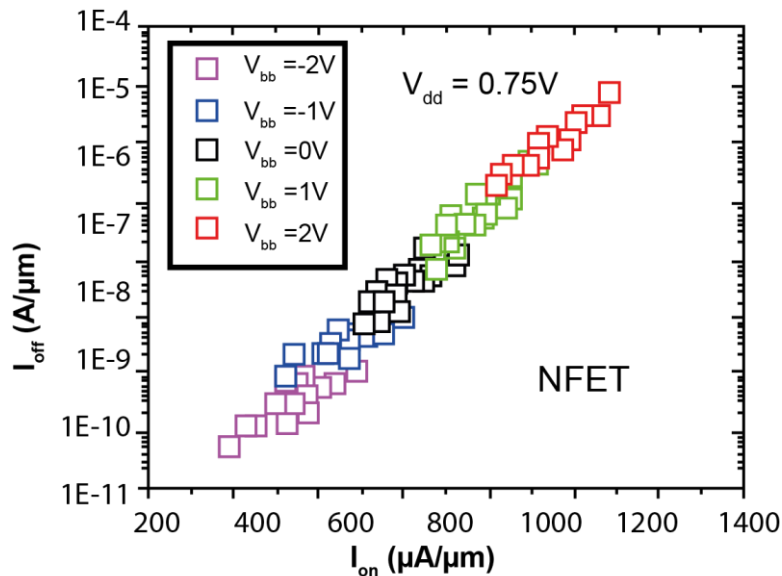
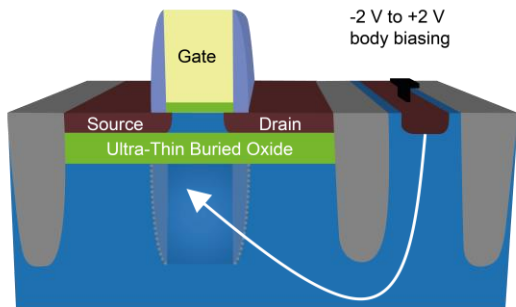


Dynamic and Leakage reduction

# Landscape of low power techniques

		BULK (Vdd only)	
Source	Parameter	Static Optimization	Dynamic Optimization
Dynamic Power	W	Multi-drive lib ✓	-
	Vdd	Multi-Vdd lib ✓	DVS ✓
	Vdd/Vth	Multi-Vdd/Vth lib ✓	✗
	F	Clock Gating ✓	DFS ✓
Leakage Power	L	Multi-L lib ✓	-
	Vth	Multi-Vth lib ✓	✗
	Switch off (Vdd)	-	Power gating ✓
Variations	Consumer (Vdd)	Static AVS ✓	✗
	Consumer & Auto (Vth)	✗	✗

# Body-bias: a unique solution to fully control threshold voltage dynamically



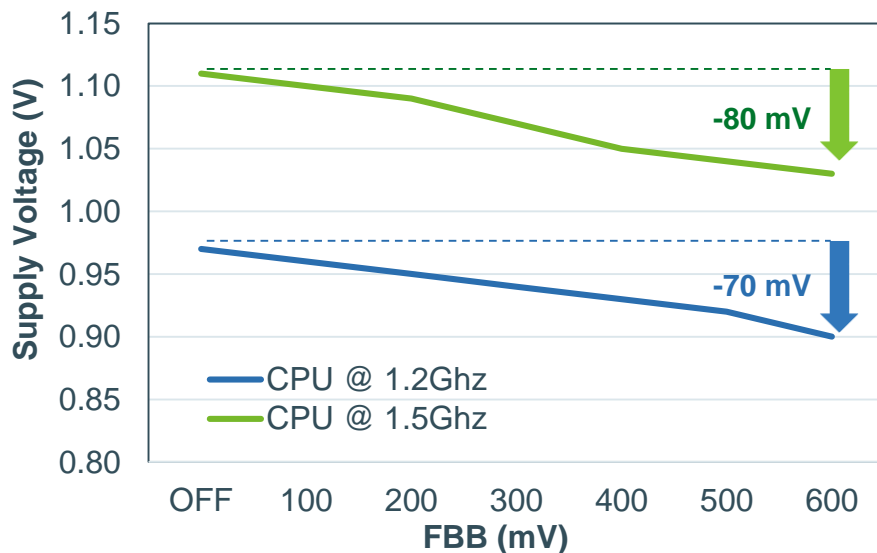
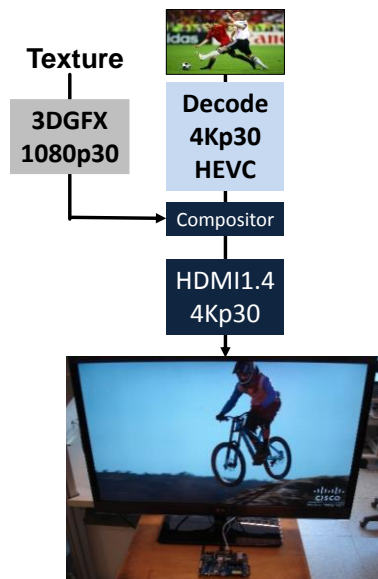
# Landscape of low power techniques

Source	Parameter	BULK (Vdd only)		FD-SOI (Vdd + Vbb)	
		Static Optimization	Dynamic Optimization	Static Optimization	Dynamic Optimization
Dynamic Power	W	Multi-drive lib ✓	-	Multi-drive lib ✓	-
	Vdd	Multi-Vdd lib ✓	DVS ✓	Multi-Vdd lib ✓	DVS ✓
	Vdd/Vth	Multi-Vdd/Vth lib ✓	✗	Multi-Vdd/Vth/BB lib ✓	DVBS ✓
	F	Clock Gating ✓	DFS ✓	Clock Gating ✓	DFS ✓
Leakage Power	L	Multi-L lib ✓	✗	Multi-L lib ✓	-
	Vth	Multi-Vth lib ✓	✗	Multi-Vth/BB lib ✓	Dynamic ABB ✓
	Switch off (Vdd)	-	Power gating ✓	-	Power gating ✓
Variations	Consumer (Vdd)	Static AVS ✓	✗	Static AVS ✓	-
	Consumer & Auto (Vth)	✗	✗	Static ABB (P) ✓	Dynamic ABB (T+A) ✓

This is very unique!!

# Adaptive optimization of body-bias and Vdd

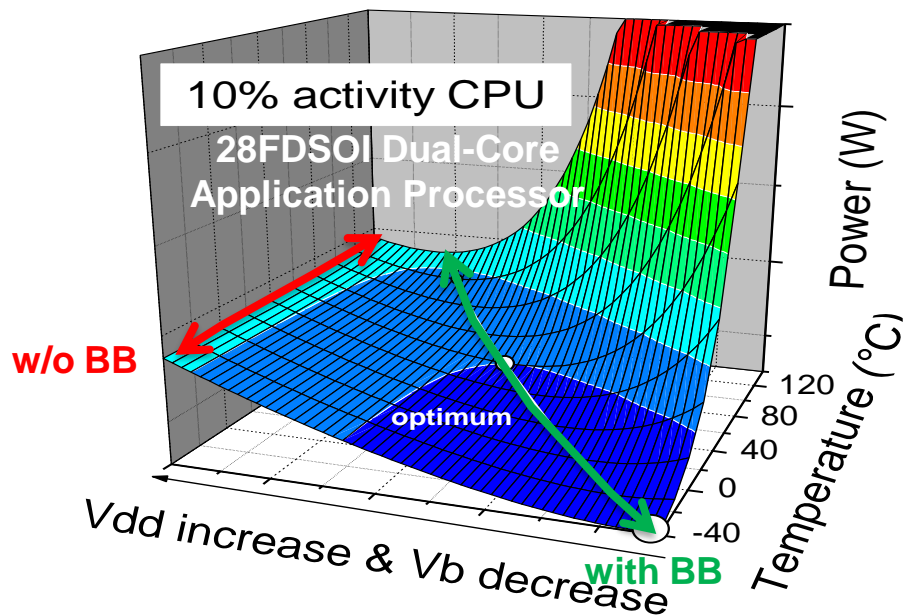
- › Adaptive body-bias is demonstrated on system running real SW
- › Body-Bias enables dynamic power reduction thanks to supply voltage reduction



ST, IRPS 2018 – Huard et al., Best Paper preselected

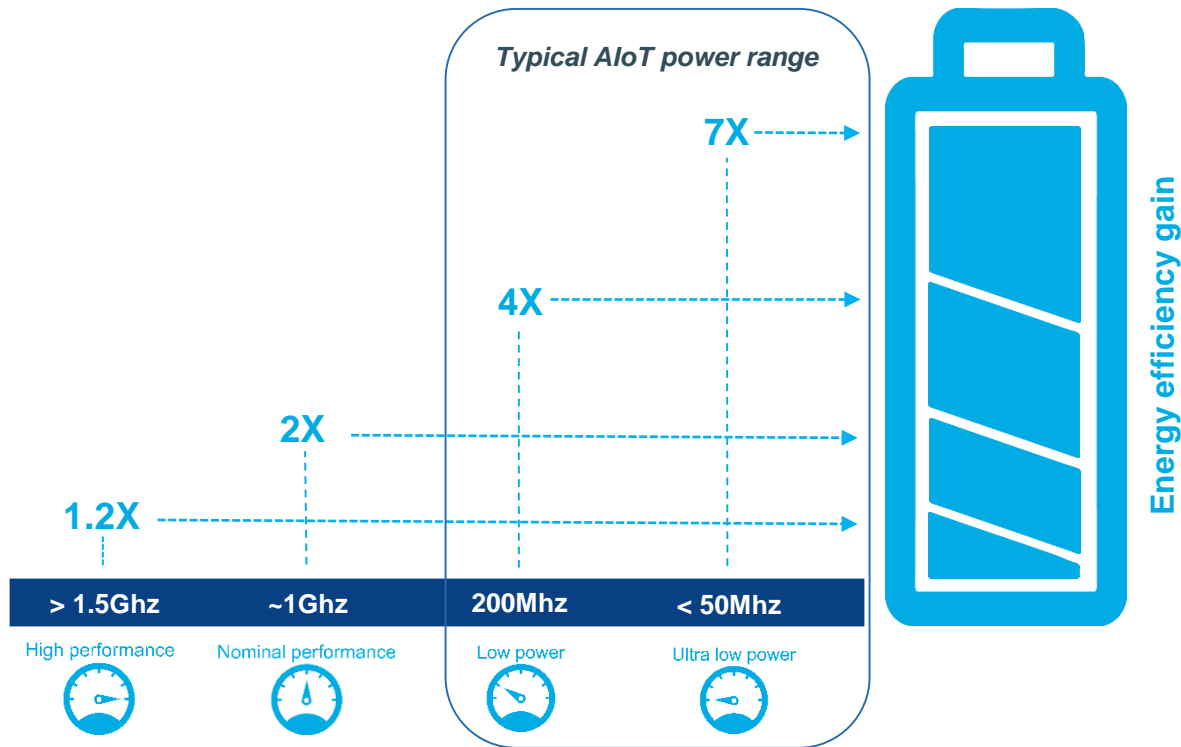
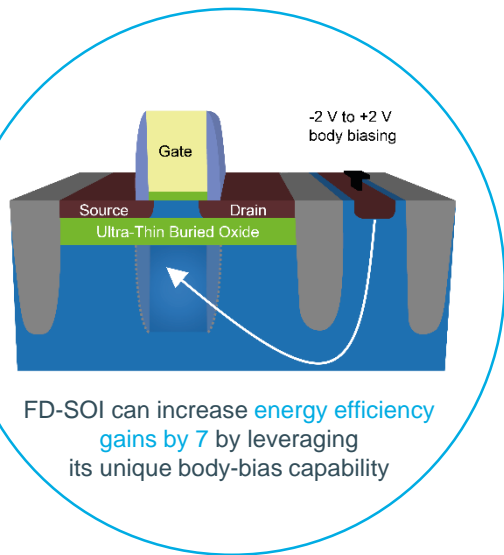
# Combining compensation and leakage optimization power mode

- › An optimum body bias / Vdd exists for each temperature
- › This optimum energy point cannot be accessed by bulk technologies



N.B. : Experimental results, ST IRPS 2016

# Body Bias



Body-bias impact (AVS, ABB) on energy efficiency

Source: Dolphin Integration, 2018

# Body-bias enablement status in the industry

BB Type	Market
Static / Boost	Mobile, Consumer, Computing
Static / Compensation	IoT, Automotive, Mobile, Consumer, Computing , A&D
Dynamic / Compensation	IoT, Automotive, Mobile, Consumer, Computing , A&D
Dynamic / Boost + Compensation	IoT, Automotive, Mobile, Consumer, Computing , A&D

Partial

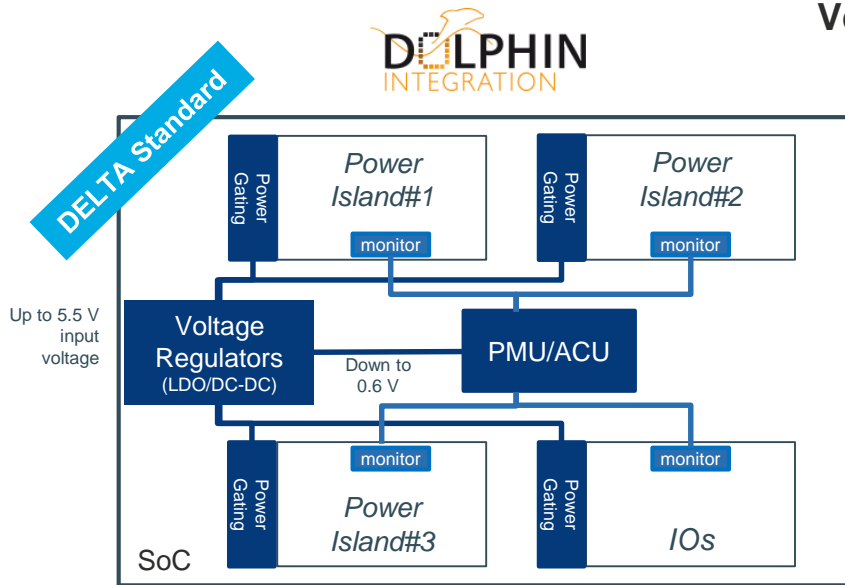
Not Started

# A complete power management IP platform...

## Current Dolphin Integration Solution :

Enablement of **advanced SoC power architecture** to bridge the complexity gap

### Vdd modulation



### Key features

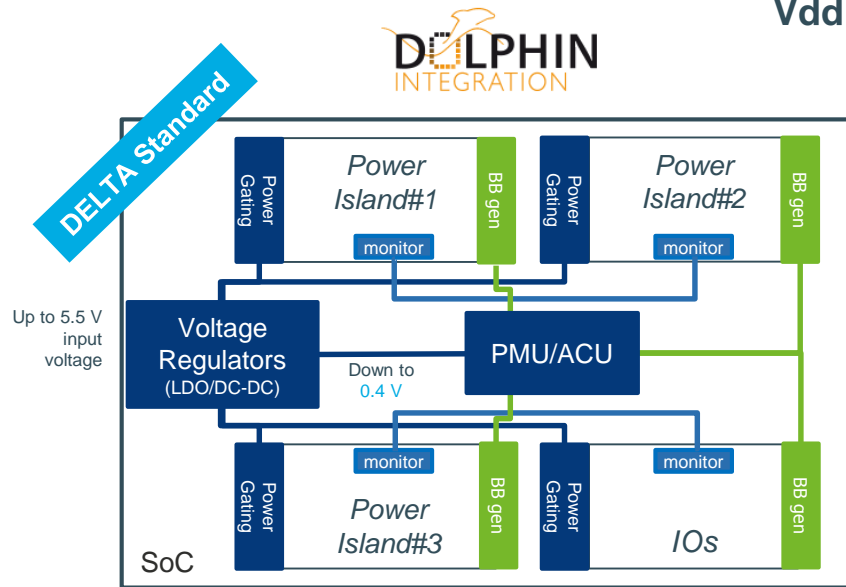
- › Wide range of IP offering
- › Standardized IPs for streamlined SoC integration
- › Scalable according to SoC complexity
- › Workable with third-party silicon IPs
- › Built-in safety features to prevent SoC failures
- › Based on silicon proven IP architectures

# ... to make body-biasing easy

## FD-SOI project – going-on :

Enablement of **Adaptive Body Biasing** as **turnkey solution** for best Energy Efficiency without risks

### Vdd + Vbb modulation



### Key evolutions

- › Enhanced Power Management IP Platform Vdd+Vbb
- › Fully integrated Power Management IP platform
- › Automatic reach of Optimum Energy Point
- › Regulation loop for P, V, T & A compensation
- › Workable with any standard-cell library & memory
- › Design methodology & support

# Enabling our customers' products shaping everyday life with engineered substrates



- › SOITEC is innovating through substrate technologies bringing solutions to tomorrow technology disruptions
- › AI and AIoT will be at the heart of the next human revolution and is moving closer to the edge
- › FD-SOI offers unique power efficiency advantages through body bias technologies
- › FD-SOI adoption in AIoT is ongoing and will play an increasing role in enabling this new technology disruption

# Thank you

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